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IRFP460C

500V N-Channel MOSFET

General Description

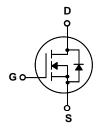
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies and power factor corrections.

Features

- 20A, 500V, $R_{DS(on)}$ = 0.24 Ω @V_{GS} = 10 V Low gate charge (typical 130nC)
- Low Crss (typical 60 pF)
- · Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		IRFP460C	Units
V _{DSS}	Drain-Source Voltage		500	V
I _D	Drain Current - Continuous (T _C = 25°C)		20	А
	- Continuous (T _C = 100	°C)	12.5	А
I _{DM}	Drain Current - Pulsed	(Note 1)	80	А
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	1050	mJ
I _{AR}	Avalanche Current	(Note 1)	20	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	23.5	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_D	Power Dissipation (T _C = 25°C)		235	W
	- Derate above 25°C		1.88	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.53	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Ch	naracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	500			V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to 25°C		0.55		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500 V, V _{GS} = 0 V			10	μΑ
		V _{DS} = 400 V, T _C = 125°C			100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 10.0 A		0.2	0.24	Ω
g _{FS}	Forward Transconductance	$V_{DS} = 50 \text{ V}, I_D = 10.0 \text{ A}$ (Note 4)		18		S
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$		4590	6000	pF
C _{iss}	Input Capacitance Output Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		380	460	pF
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	50				
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance ning Characteristics	50		380 60	460 80	pF pF
C _{iss} C _{oss} C _{rss} Switcl	Input Capacitance Output Capacitance Reverse Transfer Capacitance	f = 1.0 MHz		380 60 50	460 80 120	pF pF
C_{iss} C_{oss} C_{rss} Switcl $t_{d(on)}$ t_r	Input Capacitance Output Capacitance Reverse Transfer Capacitance ning Characteristics Turn-On Delay Time Turn-On Rise Time	50		380 60	460 80	pF pF
$egin{array}{ll} C_{iss} & \\ C_{oss} & \\ C_{rss} & \\ \hline & Switcl & \\ t_{d(on)} & \\ t_{r} & \\ t_{d(off)} & \\ \hline \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance hing Characteristics Turn-On Delay Time	f = 1.0 MHz V _{DD} = 250 V, I _D = 20 A,	 	380 60 50 150	460 80 120 310	pF pF ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{oss} \\ \end{array}$ $\begin{array}{c} C_{rss} \\ \end{array}$ $\begin{array}{c} Switcl \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance ning Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	f = 1.0 MHz V_{DD} = 250 V, I_{D} = 20 A, R_{G} = 25 Ω (Note 4, 5)	 	380 60 50 150 380	460 80 120 310 770	pF pF ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{rss} \\ \end{array}$ $\begin{array}{c} \textbf{Switcl} \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \\ Q_{g} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance Input Capacitance Reverse Transfer Capacitance Input Capacitance Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 250 \text{ V, } I_{D} = 20 \text{ A,}$ $R_{G} = 25 \Omega$ (Note 4, 5) $V_{DS} = 400 \text{ V, } I_{D} = 20 \text{ A,}$	 	380 60 50 150 380 180	120 310 770 370	pF pF ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{oss} \\ \end{array}$ $\begin{array}{c} C_{rss} \\ \end{array}$ $\begin{array}{c} Switcl \\ t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ C_g \\ C_{gs} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance ning Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time	f = 1.0 MHz V_{DD} = 250 V, I_{D} = 20 A, R_{G} = 25 Ω (Note 4, 5)	 	380 60 50 150 380 180	120 310 770 370 170	pF pF ns ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{rss} \\ \\ \hline \\ Switcl \\ t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ C_{g} \\ C_{gs} \\ C_{gd} \\ C_{gd$	Input Capacitance Output Capacitance Reverse Transfer Capacitance Ing Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 250 \text{ V}, I_{D} = 20 \text{ A},$ $R_{G} = 25 \Omega$ (Note 4, 5) $V_{DS} = 400 \text{ V}, I_{D} = 20 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)	 	380 60 50 150 380 180 130 20	120 310 770 370 170	pF pF ns ns ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{rss} \\ \\ \hline \\ Switcl \\ t_{d(on)} \\ t_r \\ t_{d(off)} \\ t_f \\ C_{g} \\ C_{gs} \\ C_{gd} \\ C_{gd$	Input Capacitance Output Capacitance Reverse Transfer Capacitance ning Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 250 \text{ V}, I_{D} = 20 \text{ A},$ $R_{G} = 25 \Omega$ (Note 4, 5) $V_{DS} = 400 \text{ V}, I_{D} = 20 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5) $(Note 4, 5)$ and Maximum Ratings	 	380 60 50 150 380 180 130 20	120 310 770 370 170	pF pF ns ns ns ns
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{oss} \\ \end{array}$ $\begin{array}{c} C_{oss} \\ C_{rss} \\ \end{array}$ $\begin{array}{c} Switcl \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \\ Q_{g} \\ Q_{gs} \\ Q_{gd} \\ \end{array}$ $\begin{array}{c} C_{gg} \\ C_{gd} \\ C_{gd$	Input Capacitance Output Capacitance Reverse Transfer Capacitance Ining Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge	$f = 1.0 \text{ MHz}$ $V_{DD} = 250 \text{ V}, I_D = 20 \text{ A},$ $R_G = 25 \Omega$ $V_{DS} = 400 \text{ V}, I_D = 20 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)	 	380 60 50 150 380 180 130 20 45	460 80 120 310 770 370 170 	pF pF ns ns ns nc nC
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{oss} \\ \end{array}$ $\begin{array}{c} C_{rss} \\ \end{array}$ $\begin{array}{c} Switcl \\ t_{d(on)} \\ t_{r} \\ t_{d(off)} \\ t_{f} \\ Q_{g} \\ Q_{gs} \\ Q_{gd} \\ \end{array}$ $\begin{array}{c} Drain-S \\ I_{SM} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance Ining Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics and Maximum Continuous Drain-Source Diode	$f = 1.0 \text{ MHz}$ $V_{DD} = 250 \text{ V}, I_D = 20 \text{ A},$ $R_G = 25 \Omega$ $V_{DS} = 400 \text{ V}, I_D = 20 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)	 	380 60 50 150 380 180 130 20 45	460 80 120 310 770 370 170 	pF pF ns ns ns nc nC
$\begin{array}{c} C_{iss} \\ C_{oss} \\ C_{rss} \\ \end{array}$ $\begin{array}{c} \textbf{Switcl} \\ \textbf{t}_{d(on)} \\ \textbf{t}_{r} \\ \textbf{t}_{d(off)} \\ \textbf{t}_{f} \\ \textbf{Q}_{g} \\ \textbf{Q}_{gs} \\ \textbf{Q}_{gd} \\ \end{array}$ $\begin{array}{c} \textbf{Drain-S} \\ \textbf{I}_{s} \\ \end{array}$	Input Capacitance Output Capacitance Reverse Transfer Capacitance ning Characteristics Turn-On Delay Time Turn-On Rise Time Turn-Off Delay Time Turn-Off Fall Time Total Gate Charge Gate-Source Charge Gate-Drain Charge Source Diode Characteristics at Maximum Continuous Drain-Source Diode Fall Time Maximum Pulsed Drain-Source Diode Fall Time	$f = 1.0 \text{ MHz}$ $V_{DD} = 250 \text{ V}, I_D = 20 \text{ A},$ $R_G = 25 \Omega$ $V_{DS} = 400 \text{ V}, I_D = 20 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5) $\text{Ad Maximum Ratings}$ $\text{ode Forward Current}$ Forward Current	 	380 60 150 380 180 130 20 45	460 80 310 770 370 170 	pF pF ns ns ns nc nC

- $\label{eq:Notes:1} \begin{tabular}{ll} \textbf{Notes:} \\ 1. & \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature} \\ 2. & \textbf{L} = 5.1 \text{mH, } |_{AS} = 20 \text{A, } |_{DD} = 50 \text{V, } |_{RG} = 25 \ \Omega, \text{ Starting } |_{J} = 25 \ \text{°C} \\ 3. & \textbf{l}_{SD} \leq 20 \text{A, } \text{didd} \leq 200 \text{A/µs, } |_{DD} \leq \text{BV}_{DSS}, \text{ Starting } |_{J} = 25 \ \text{°C} \\ 4. & \textbf{Pulse Test: Pulse width} \leq 300 \ \mu\text{s, Duty cycle} \leq 2 \ \text{\%} \\ 5. & \textbf{Essentially independent of operating temperature} \\ \end{tabular}$

Typical Characteristics

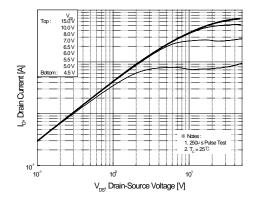


Figure 1. On-Region Characteristics

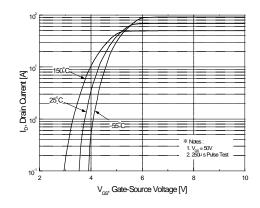


Figure 2. Transfer Characteristics

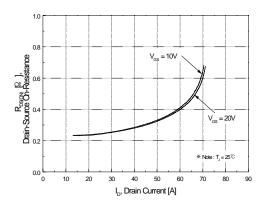


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

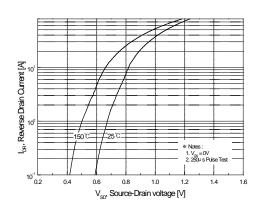


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

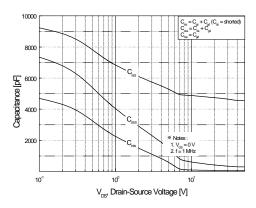


Figure 5. Capacitance Characteristics

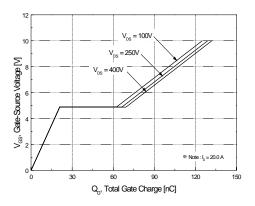


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

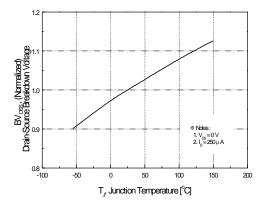
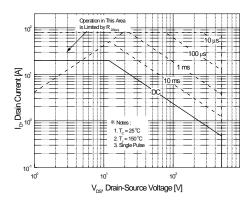


Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



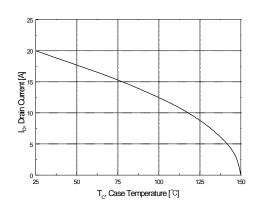


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

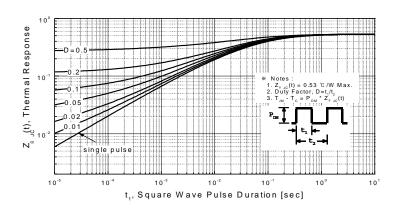
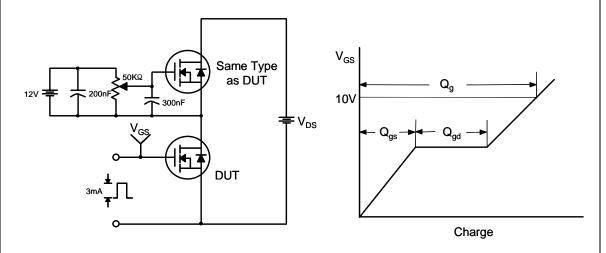
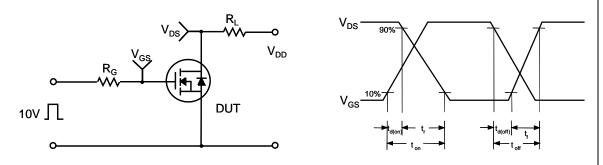


Figure 11. Transient Thermal Response Curve

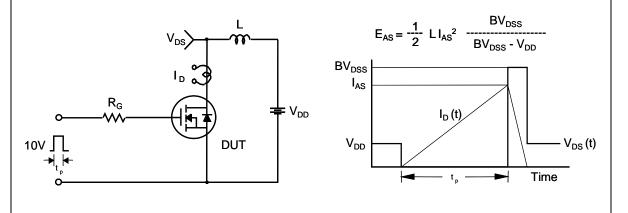
Gate Charge Test Circuit & Waveform



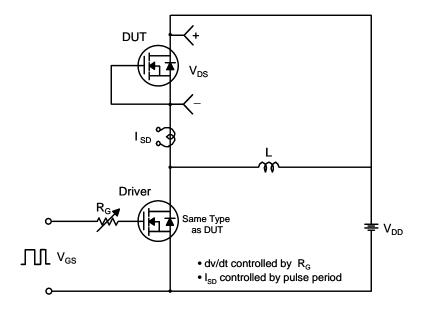
Resistive Switching Test Circuit & Waveforms

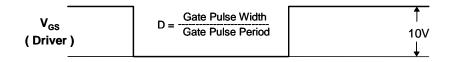


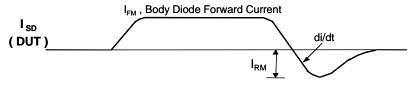
Unclamped Inductive Switching Test Circuit & Waveforms



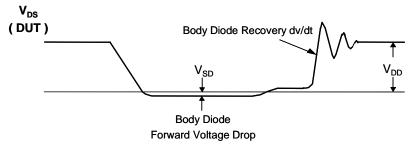
Peak Diode Recovery dv/dt Test Circuit & Waveforms





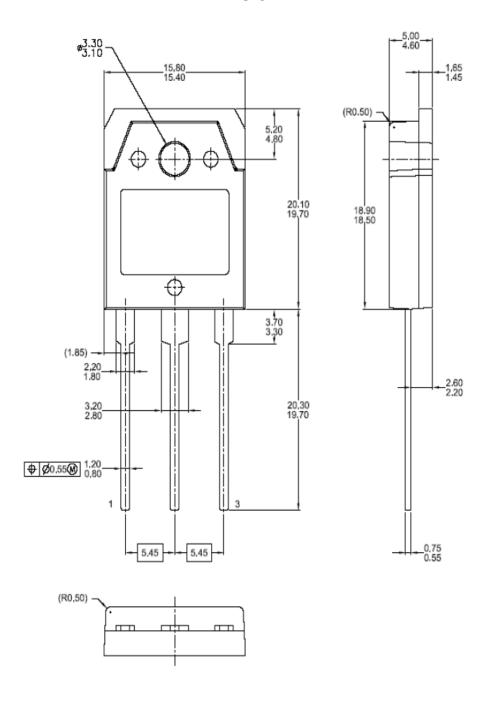


Body Diode Reverse Current





TO-3PN



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